

ALL RIGHTS
RESERVED

**SEMICONDUCTOR DEVICE HAVING MULTI-CHIP
PACKAGE STRUCTURE**

Inventors: Shibaek Nam
Oseob Jeon
Chulho Heo

5

ABSTRACT

10 A semiconductor device having a multi-chip package structure and a
manufacturing method therefor are provided. The semiconductor device includes a lead
frame, a first integrated circuit chip, and a second integrated circuit chip. The first
integrated circuit chip is attached to a top surface of the lead frame by a conductive
adhesive, and the second integrated circuit chip is attached to a top surface of the first
integrated circuit chip by an insulating adhesive tape or an insulation epoxy adhesive.

15